

FIG. 1B
PRIOR ART

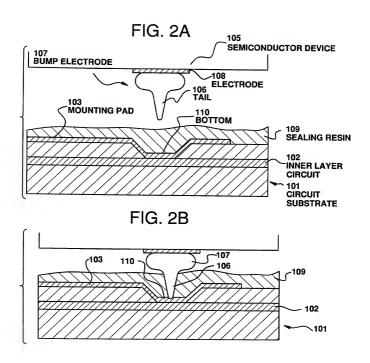
SEMICONDUCTOR DEVICE

SENCAPSULATING RESIN

MOUNTING PAD

2
INSULATING RESIN
LAYER

1
SUBSTRATE



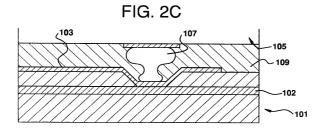
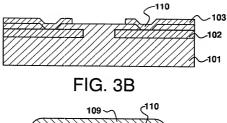


FIG. 3A



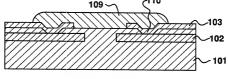


FIG. 3C

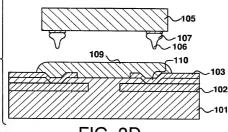
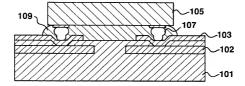


FIG. 3D



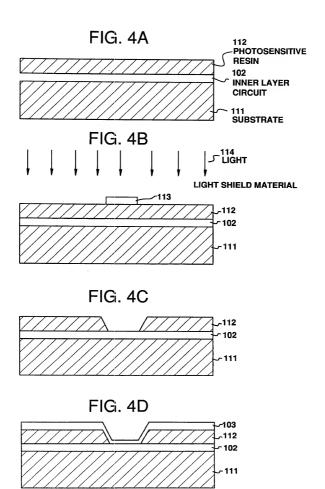


FIG. 5A

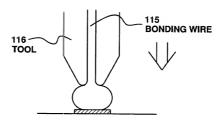


FIG. 5B

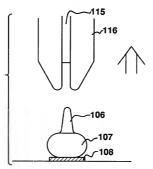
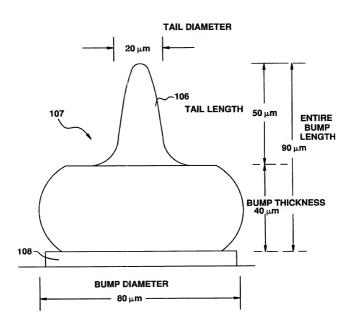
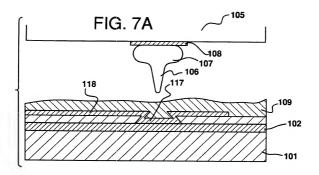
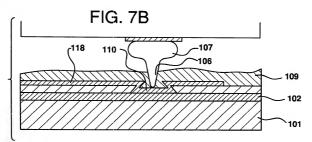


FIG. 6







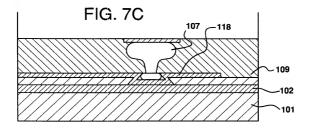


FIG. 8A

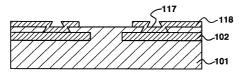


FIG. 8B

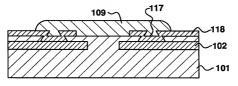


FIG. 8C

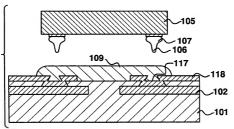


FIG. 8D

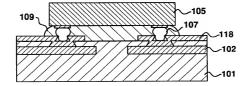


FIG. 9A

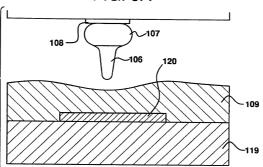


FIG. 9B

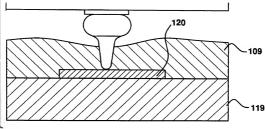
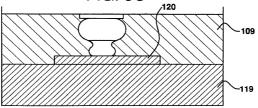


FIG. 9C



_, and amended on

Priority Claimed (yes or no)

yes

Status

(patented, pending, abandoned)

(for declaration not accompanying application)

Filing Date

July 27, 1995

which application is:

If the attached application

(for original application)

Application Number

Application Serial No.

191737/1995

DECLARATION AND POWER OF ATTORNEY

As a below named inventor, I hereby declare that my residence, post office address and citizenship are as stated below next to my name: that I verily believe I am the original, first and sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of the subject matter claimed and for which a patent is sought in the application entitled:

□ application Serial No._

that I have reviewed and understand the contents of the specification of the above-identified application, including the claims, as amended by any amendment referred to above; that I acknowledge my duty to disclose information of which I am aware and which is material to the examination of this application under 37 C.F.R. 1.56; and that I hereby claim foreign priority benefits under Title 35, United States Code §119, §172 or §365 of any foreign application(s) for patent or inventor's certificate listed below and have also identified on said list any foreign application for patent or inventor's certificate on this invention having a filing date before that of the application on which priority is claimed:

I hereby claim the benefit of Title 35, United States Code §120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in a listed prior United States application in the manner provided by the first paragraph of Title 35, United States Code, §112, I acknowledge my duty to disclose any material information under 37 C.F.R. 1.56 which occurred between the filing date of the prior

Filing Date

I hereby appoint John H. Mion, Reg. No. 18,879; Donald E. Zinn, Reg. No. 19,046; Thomas J. Macpeak, Reg. No. 19,292; Robert J. Seas, Jr., Reg. No. 21,092; Darryl Mexic, Reg. No. 23,063; Robert V. Sloan, Reg. No. 22,775; Peter D. Olexy,

Reg. No. 24,513; J. Frank Osha, Reg. No. 24,625; Waddell A. Biggart, Reg. No. 24,861; Robert G. McMorrow, Reg. No.

filed

Country

Japan

application and the national or PCT international filing date of this application: .

METHOD OF MOUNTING A SEMICONDUCTOR DEVICE TO A SUBSTRATE AND A MOUNTED STRUCTURE

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I hereby declare that all statements information and belief are believed willful false statements and the like Title 18 of the United States Code ar or any patent issuing thereon.	to be true; and further that the so made are punishable by fin	se statements were made wit e or imprisonment, or both, i	h the knowledge tha under Section 1001 o
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